



SN74LS259(LX) 8-bit addressable latch

Product Specification

Specification Revision History:

Version	Date	Description
2022-12-A2	2022-12	New
2023-04-B1	2023-04	Update the template



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1、General Description

The SN74LS259 is an 8-bit addressable latch. The device features four modes of operation. In the addressable latch mode, data on the D input is written into the latch addressed by the inputs A0 to A3. The addressed latch will follow the data input, non-addressed latches will retain their previous states. In memory mode, all latches retain their previous states and are unaffected by the data or address inputs. In the 3-to-8 decoding or demultiplexing mode, the addressed output follows the D input and all other outputs are LOW. In the reset mode, all outputs are forced LOW and unaffected by the data or address inputs. Inputs include clamp diodes. This enables the use of current limiting resistors to interface inputs to voltages in excess of V_{CC} .

Features:

- Combined demultiplexer and 8-bit latch
- Serial-to-parallel capability
- Output from each storage bit available
- Random (addressable) data entry
- Easily expandable
- Common reset input
- Useful as a 3-to-8 active HIGH decoder
- Specified from -40°C to $+125^{\circ}\text{C}$
- Packaging information: DIP16/SOP16/TSSOP16



Ordering Information:

Tube packing specifications:

Part number	Packaging form	Marking code	Tube quantity	Boxed tube quantity	Boxed quantity	Notes
SN74LS259N(LX)	DIP16	SN74LS259N	25 PCS/tube	40 tube/box	1000 PCS/box	Dimensions of plastic enclosure: 19.0mm×6.4mm Pin spacing: 2.54mm

Reel packing specifications:

Part number	Packaging form	Marking code	Reel quantity	Boxed reel quantity	Notes
SN74LS259BDR(LX)	SOP16	LS259	4000 PCS/reel	8000 PCS/box	Dimensions of plastic enclosure: 10.0mm×3.9mm Pin spacing:1.27mm
SN74LS259PW(LX)	TSSOP16	LS259	5000 PCS/reel	10000 PCS/box	Dimensions of plastic enclosure: 5.0mm×4.4mm Pin spacing:0.65mm

Note: If the physical information is inconsistent with the ordering information, please refer to the actual product.

2、Block Diagram And Pin Description

2.1、Block Diagram

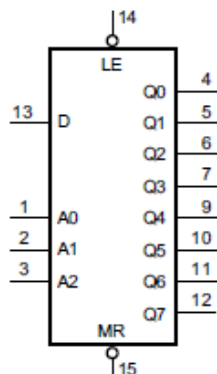


Figure 1. Logic symbol

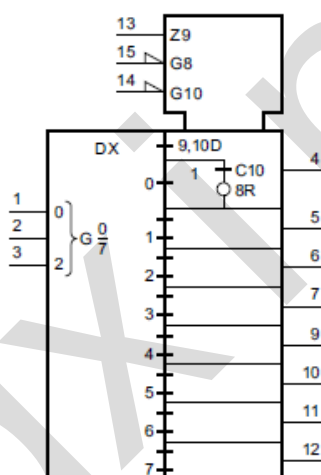


Figure 2. Functional diagram

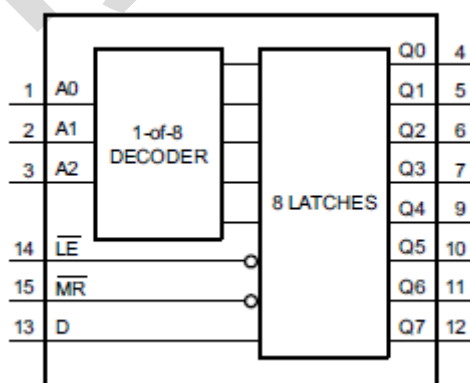
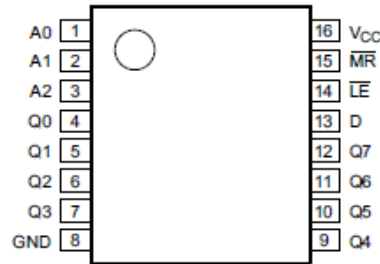


Figure 3. Functional diagram



2.2、Pin Configurations



2.3、Pin Description

Pin No.	Pin Name	Description
1	A0	address input
2	A1	address input
3	A2	address input
4	Q0	latch output
5	Q1	latch output
6	Q2	latch output
7	Q3	latch output
8	GND	ground (0V)
9	Q4	latch output
10	Q5	latch output
11	Q6	latch output
12	Q7	latch output
13	D	data input
14	LE	latch enable input (active LOW)
15	MR	conditional reset input (active LOW)
16	V _{CC}	supply voltage

2.4、Function Table

Operating mode	Input						Output							
	MR	LE	D	A0	A1	A2	Q0	Q1	Q2	Q3	Q4	Q5	Q6	Q7
Reset (clear)	L	H	X	X	X	X	L	L	L	L	L	L	L	L
Demultiplexer (active HIGH 8-channel) decoder (when D=H)	L	L	d	L	L	L	Q=d	L	L	L	L	L	L	L
	L	L	d	H	L	L	L	Q=d	L	L	L	L	L	L
	L	L	d	L	H	L	L	L	Q=d	L	L	L	L	L
	L	L	d	H	H	L	L	L	L	Q=d	L	L	L	L
	L	L	d	L	L	H	L	L	L	L	Q=d	L	L	L
	L	L	d	H	L	H	L	L	L	L	L	Q=d	L	L
	L	L	d	L	H	H	L	L	L	L	L	L	Q=d	L
	L	L	d	H	H	H	L	L	L	L	L	L	L	Q=d
Memory	H	H	X	X	X	X	q ₀	q ₁	q ₂	q ₃	q ₄	q ₅	q ₆	q ₇



(no action)														
Addressable latch	H	L	d	L	L	L	Q=d	q ₁	q ₂	q ₃	q ₄	q ₅	q ₆	q ₇
	H	L	d	H	L	L	q ₀	Q=d	q ₂	q ₃	q ₄	q ₅	q ₆	q ₇
	H	L	d	L	H	L	q ₀	q ₁	Q=d	q ₃	q ₄	q ₅	q ₆	q ₇
	H	L	d	H	H	L	q ₀	q ₁	q ₂	Q=d	q ₄	q ₅	q ₆	q ₇
	H	L	d	L	L	H	q ₀	q ₁	q ₂	q ₃	Q=d	q ₅	q ₆	q ₇
	H	L	d	H	L	H	q ₀	q ₁	q ₂	q ₃	q ₄	Q=d	q ₆	q ₇
	H	L	d	L	H	H	q ₀	q ₁	q ₂	q ₃	q ₄	q ₅	Q=d	q ₇
	H	L	d	H	H	H	q ₀	q ₁	q ₂	q ₃	q ₄	q ₅	q ₆	Q=d

Note:

[1] H=HIGH voltage level; L=LOW voltage level; X=don't care.

[2] d=HIGH or LOW data one set-up time prior to the LOW-to-HIGH $\overline{LE}$ transition.

[3] q=lower case letter indicates the state of the referenced input one set-up time prior to the LOW-to-HIGH transition.

2.5、Operating Mode Select Table

$\overline{LE}$	$\overline{MR}$	Mode
L	H	Addressable latch mode
H	H	Memory mode
L	L	Demultiplexer mode
H	L	Reset mode

Note: H=HIGH voltage level; L=LOW voltage level.

3、Electrical Parameter

3.1、Absolute Maximum Ratings

(Voltages are referenced to GND (ground=0V), unless otherwise specified.)

Parameter	Symbol	Conditions	Min.	Max.	Unit
supply voltage	V_{CC}	-	-0.5	+7.0	V
input clamping current	I_{IK}	$V_I < -0.5V$ or $V_I > V_{CC}+0.5V$	-	± 20	mA
output clamping current	I_{OK}	$V_O < -0.5V$ or $V_O > V_{CC}+0.5V$	-	± 20	mA
output current	I_O	$V_O = -0.5V$ to $(V_{CC}+0.5V)$	-	± 25	mA
supply current	I_{CC}	-	-	+70	mA
ground current	I_{GND}	-	-70	-	mA
storage temperature	T_{stg}	-	-65	+150	°C
total power dissipation	P_{tot}	-	-	500	mW
Soldering temperature	T_L	10s	DIP	245	°C
			SOP/TSSOP	260	°C



3.2、Recommended Operating Conditions

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
supply voltage	V_{CC}	-	2.0	5.0	6.0	V
input voltage	V_I	-	0	-	V_{CC}	V
output voltage	V_O	-	0	-	V_{CC}	V
input transition rise and fall rate	$\Delta t/\Delta V$	$V_{CC}=2.0V$	-	-	625	ns/V
		$V_{CC}=4.5V$	-	1.67	139	ns/V
		$V_{CC}=6.0V$	-	-	83	ns/V
ambient temperature	T_{amb}	-	-40	-	+125	°C

3.3、Electrical Characteristics

3.3.1、DC Characteristics 1

($T_{amb}=25^{\circ}C$, voltages are referenced to GND (ground=0V), unless otherwise specified.)

Parameter	Symbol	Conditions		Min.	Typ.	Max.	Unit
HIGH-level input voltage	V _{IH}	V _{CC} =2.0V		1.5	1.2	-	V
		V _{CC} =4.5V		3.15	2.4	-	V
		V _{CC} =6.0V		4.2	3.2	-	V
LOW-level input voltage	V _{IL}	V _{CC} =2.0V		-	0.8	0.5	V
		V _{CC} =4.5V		-	2.1	1.35	V
		V _{CC} =6.0V		-	2.8	1.8	V
HIGH-level output voltage	V _{OH}	V _I = V _{IH} or V _{IL}	I _O =-20uA; V _{CC} =2.0V	1.9	2.0	-	V
			I _O =-20uA; V _{CC} =4.5V	4.4	4.5	-	V
			I _O =-20uA; V _{CC} =6.0V	5.9	6.0	-	V
			I _O =-4.0mA; V _{CC} =4.5V	3.98	4.32	-	V
			I _O =-5.2mA; V _{CC} =6.0V	5.48	5.81	-	V
LOW-level output voltage	V _{OL}	V _I = V _{IH} or V _{IL}	I _O =20uA; V _{CC} =2.0V	-	0	0.1	V
			I _O =20uA; V _{CC} =4.5V	-	0	0.1	V
			I _O =20uA; V _{CC} =6.0V	-	0	0.1	V
			I _O =4.0mA; V _{CC} =4.5V	-	0.15	0.26	V
			I _O =5.2mA; V _{CC} =6.0V	-	0.16	0.26	V
input leakage current	I _I	V _I =V _{CC} or GND; V _{CC} =6.0V		-	-	±1.0	uA
supply current	I _{CC}	V _I =V _{CC} or GND; I _O =0A; V _{CC} =6.0V		-	-	8.0	uA
input capacitance	C _I	-		-	3.5	-	pF



3.3.2、DC Characteristics 2

($T_{amb} = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$, voltages are referenced to GND (ground=0V), unless otherwise specified.)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
HIGH-level input voltage	V_{IH}	$V_{CC}=2.0\text{V}$	1.5	-	-	V
		$V_{CC}=4.5\text{V}$	3.15	-	-	V
		$V_{CC}=6.0\text{V}$	4.2	-	-	V
LOW-level input voltage	V_{IL}	$V_{CC}=2.0\text{V}$	-	-	0.5	V
		$V_{CC}=4.5\text{V}$	-	-	1.35	V
		$V_{CC}=6.0\text{V}$	-	-	1.8	V
HIGH-level output voltage	V_{OH}	$V_I = V_{IH}$ or V_{IL} $I_O = -20\mu\text{A}; V_{CC}=2.0\text{V}$	1.9	-	-	V
		$I_O = -20\mu\text{A}; V_{CC}=4.5\text{V}$	4.4	-	-	V
		$I_O = -20\mu\text{A}; V_{CC}=6.0\text{V}$	5.9	-	-	V
		$I_O = -4.0\text{mA}; V_{CC}=4.5\text{V}$	3.84	-	-	V
		$I_O = -5.2\text{mA}; V_{CC}=6.0\text{V}$	5.34	-	-	V
LOW-level output voltage	V_{OL}	$V_I = V_{IH}$ or V_{IL} $I_O = 20\mu\text{A}; V_{CC}=2.0\text{V}$	-	-	0.1	V
		$I_O = 20\mu\text{A}; V_{CC}=4.5\text{V}$	-	-	0.1	V
		$I_O = 20\mu\text{A}; V_{CC}=6.0\text{V}$	-	-	0.1	V
		$I_O = 4.0\text{mA}; V_{CC}=4.5\text{V}$	-	-	0.33	V
		$I_O = 5.2\text{mA}; V_{CC}=6.0\text{V}$	-	-	0.33	V
input leakage current	I_I	$V_I = V_{CC}$ or GND; $V_{CC}=6.0\text{V}$	-	-	± 1.0	μA
supply current	I_{CC}	$V_I = V_{CC}$ or GND; $I_O = 0\text{A}; V_{CC}=6.0\text{V}$	-	-	80	μA
input capacitance	C_I	-	-	-	-	pF



3.3.3、DC Characteristics 3

($T_{amb} = -40^{\circ}\text{C}$ to $+125^{\circ}\text{C}$, voltages are referenced to GND (ground=0V), unless otherwise specified.)

Parameter	Symbol	Conditions		Min.	Typ.	Max.	Unit
HIGH-level input voltage	V _{IH}	V _{CC} =2.0V		1.5	-	-	V
		V _{CC} =4.5V		3.15	-	-	V
		V _{CC} =6.0V		4.2	-	-	V
LOW-level input voltage	V _{IL}	V _{CC} =2.0V		-	-	0.5	V
		V _{CC} =4.5V		-	-	1.35	V
		V _{CC} =6.0V		-	-	1.8	V
HIGH-level output voltage	V _{OH}	V _I = V _{IH} or V _{IL}	I _O =-20uA; V _{CC} =2.0V	1.9	-	-	V
			I _O =-20uA; V _{CC} =4.5V	4.4	-	-	V
			I _O =-20uA; V _{CC} =6.0V	5.9	-	-	V
			I _O =-4.0mA; V _{CC} =4.5V	3.7	-	-	V
			I _O =-5.2mA; V _{CC} =6.0V	5.2	-	-	V
LOW-level output voltage	V _{OL}	V _I = V _{IH} or V _{IL}	I _O =20uA; V _{CC} =2.0V	-	-	0.1	V
			I _O =20uA; V _{CC} =4.5V	-	-	0.1	V
			I _O =20uA; V _{CC} =6.0V	-	-	0.1	V
			I _O =4.0mA; V _{CC} =4.5V	-	-	0.4	V
			I _O =5.2mA; V _{CC} =6.0V	-	-	0.4	V
input leakage current	I _I	V _I =V _{CC} or GND; V _{CC} =6.0V		-	-	±1.0	uA
supply current	I _{CC}	V _I =V _{CC} or GND; I _O =0A; V _{CC} =6.0V		-	-	160	uA
input capacitance	C _I	-		-	-	-	pF

3.3.4、AC Characteristics 1

($T_{amb} = 25^{\circ}\text{C}$, voltages are referenced to GND (ground=0V), unless otherwise specified.)

Parameter	Symbol	Conditions		Min.	Typ.	Max.	Unit
propagation delay	t _{pd}	D to Qn; see Figure 5	V _{CC} =2.0V	-	58	185	ns
			V _{CC} =4.5V	-	21	37	ns
			V _{CC} =5.0V; C _L =15pF	-	18	-	ns
			V _{CC} =6.0V	-	17	31	ns
		An to Qn; see Figure 6	V _{CC} =2.0V	-	58	185	ns
			V _{CC} =4.5V	-	21	37	ns
			V _{CC} =5.0V; C _L =15pF	-	17	-	ns
			V _{CC} =6.0V	-	17	31	ns
		LE to Qn; see Figure 7	V _{CC} =2.0V	-	55	170	ns
			V _{CC} =4.5V	-	20	34	ns
			V _{CC} =5.0V; C _L =15pF	-	17	-	ns
			V _{CC} =6.0V	-	16	29	ns



HIGH to LOW propagation delay	t_{PHL}	$\overline{MR}$ to Q_n ; see Figure 8	$V_{CC}=2.0V$	-	50	155	ns
			$V_{CC}=4.5V$	-	18	31	ns
			$V_{CC}=5.0V$; $C_L=15pF$	-	15	-	ns
			$V_{CC}=6.0V$	-	14	26	ns
transition time	t_t	see Figure 7	$V_{CC}=2.0V$	-	19	75	ns
			$V_{CC}=4.5V$	-	7	15	ns
			$V_{CC}=6.0V$	-	6	13	ns
pulse width	t_w	$\overline{LE}$ HIGH or LOW; see Figure 7	$V_{CC}=2.0V$	70	17	-	ns
			$V_{CC}=4.5V$	14	6	-	ns
			$V_{CC}=6.0V$	12	5	-	ns
		$\overline{MR}$ LOW; see Figure 8	$V_{CC}=2.0V$	70	17	-	ns
			$V_{CC}=4.5V$	14	6	-	ns
			$V_{CC}=6.0V$	12	5	-	ns
set-up time	t_{su}	D, A_n to $\overline{LE}$; see Figure 9 and Figure 10	$V_{CC}=2.0V$	80	19	-	ns
			$V_{CC}=4.5V$	16	7	-	ns
			$V_{CC}=6.0V$	14	6	-	ns
hold time	t_h	D to $\overline{LE}$; see Figure 9 and Figure 10	$V_{CC}=2.0V$	0	-19	-	ns
			$V_{CC}=4.5V$	0	-6	-	ns
		A_n to $\overline{LE}$; see Figure 9 and Figure 10	$V_{CC}=6.0V$	0	-5	-	ns
			$V_{CC}=2.0V$	2	-11	-	ns
			$V_{CC}=4.5V$	2	-4	-	ns
			$V_{CC}=6.0V$	2	-3	-	ns
power dissipation capacitance	C_{PD}	$f_i=1MHz$; $V_I=GND$ to V_{CC}		-	19	-	pF

Note:

[1] Typical values are measured at nominal supply voltage ($V_{CC}=3.3V$ and $V_{CC}=5.0V$).[2] t_{pd} is the same as t_{PLH} and t_{PHL} .[3] t_t is the same as t_{THL} and t_{TLH} .[4] C_{PD} is used to determine the dynamic power dissipation (P_D in μW). $P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \sum (C_L \times V_{CC}^2 \times f_o)$ where: f_i =input frequency in MHz; f_o =output frequency in MHz; C_L =output load capacitance in pF; V_{CC} =supply voltage in V; N =number of inputs switching; $\sum (C_L \times V_{CC}^2 \times f_o)$ =sum of outputs.



3.3.5、AC Characteristics 2

($T_{amb} = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$, voltages are referenced to GND (ground=0V), unless otherwise specified.)

Parameter	Symbol	Conditions		Min.	Typ.	Max.	Unit
propagation delay	t_{pd}	D to Qn; see Figure 5	$V_{CC}=2.0\text{V}$	-	-	230	ns
			$V_{CC}=4.5\text{V}$	-	-	46	ns
			$V_{CC}=5.0\text{V}; C_L=15\text{pF}$	-	-	-	ns
			$V_{CC}=6.0\text{V}$	-	-	39	ns
		An to Qn; see Figure 6	$V_{CC}=2.0\text{V}$	-	-	230	ns
			$V_{CC}=4.5\text{V}$	-	-	46	ns
			$V_{CC}=5.0\text{V}; C_L=15\text{pF}$	-	-	-	ns
			$V_{CC}=6.0\text{V}$	-	-	39	ns
		$\overline{\text{LE}}$ to Qn; see Figure 7	$V_{CC}=2.0\text{V}$	-	-	215	ns
			$V_{CC}=4.5\text{V}$	-	-	43	ns
			$V_{CC}=5.0\text{V}; C_L=15\text{pF}$	-	-	-	ns
			$V_{CC}=6.0\text{V}$	-	-	37	ns
HIGH to LOW propagation delay	t_{PHL}	$\overline{\text{MR}}$ to Qn; see Figure 8	$V_{CC}=2.0\text{V}$	-	-	195	ns
			$V_{CC}=4.5\text{V}$	-	-	39	ns
			$V_{CC}=5.0\text{V}; C_L=15\text{pF}$	-	-	-	ns
			$V_{CC}=6.0\text{V}$	-	-	33	ns
transition time	t_t	see Figure 7	$V_{CC}=2.0\text{V}$	-	-	95	ns
			$V_{CC}=4.5\text{V}$	-	-	19	ns
			$V_{CC}=6.0\text{V}$	-	-	16	ns
pulse width	t_w	$\overline{\text{LE}}$ HIGH or LOW; see Figure 7	$V_{CC}=2.0\text{V}$	90	-	-	ns
			$V_{CC}=4.5\text{V}$	18	-	-	ns
			$V_{CC}=6.0\text{V}$	15	-	-	ns
		$\overline{\text{MR}}$ LOW; see Figure 8	$V_{CC}=2.0\text{V}$	90	-	-	ns
			$V_{CC}=4.5\text{V}$	18	-	-	ns
			$V_{CC}=6.0\text{V}$	15	-	-	ns
set-up time	t_{su}	D, An to $\overline{\text{LE}}$; see Figure 9 and Figure 10	$V_{CC}=2.0\text{V}$	100	-	-	ns
			$V_{CC}=4.5\text{V}$	20	-	-	ns
			$V_{CC}=6.0\text{V}$	17	-	-	ns
hold time	t_h	D to $\overline{\text{LE}}$; see Figure 9 and Figure 10	$V_{CC}=2.0\text{V}$	0	-	-	ns
			$V_{CC}=4.5\text{V}$	0	-	-	ns
			$V_{CC}=6.0\text{V}$	0	-	-	ns
		An to $\overline{\text{LE}}$; see Figure 9 and Figure 10	$V_{CC}=2.0\text{V}$	2	-	-	ns
			$V_{CC}=4.5\text{V}$	2	-	-	ns
			$V_{CC}=6.0\text{V}$	2	-	-	ns
power dissipation capacitance	C_{PD}	$f_i=1\text{MHz}; V_I=\text{GND to } V_{CC}$		-	-	-	pF



Note:

[1] Typical values are measured at nominal supply voltage ($V_{CC}=3.3V$ and $V_{CC}=5.0V$).

[2] t_{pd} is the same as t_{PLH} and t_{PHL} .

[3] t_t is the same as t_{THL} and t_{TLH} .

[4] C_{PD} is used to determine the dynamic power dissipation (P_D in μW).

$$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \sum (C_L \times V_{CC}^2 \times f_o) \text{ where:}$$

f_i =input frequency in MHz;

f_o =output frequency in MHz;

C_L =output load capacitance in pF;

V_{CC} =supply voltage in V;

N =number of inputs switching;

$\sum (C_L \times V_{CC}^2 \times f_o)$ =sum of outputs.

3.3.6、AC Characteristics 3

($T_{amb}=-40^{\circ}C$ to $+125^{\circ}C$, voltages are referenced to GND (ground=0V), unless otherwise specified.)

Parameter	Symbol	Conditions		Min.	Typ.	Max.	Unit
propagation delay	t _{pd}	D to Qn; see Figure 5	V _{CC} =2.0V	-	-	280	ns
			V _{CC} =4.5V	-	-	56	ns
			V _{CC} =5.0V; C _L =15pF	-	-	-	ns
			V _{CC} =6.0V	-	-	48	ns
		An to Qn; see Figure 6	V _{CC} =2.0V	-	-	280	ns
			V _{CC} =4.5V	-	-	56	ns
			V _{CC} =5.0V; C _L =15pF	-	-	-	ns
			V _{CC} =6.0V	-	-	48	ns
		LE to Qn; see Figure 7	V _{CC} =2.0V	-	-	255	ns
			V _{CC} =4.5V	-	-	51	ns
			V _{CC} =5.0V; C _L =15pF	-	-	-	ns
			V _{CC} =6.0V	-	-	43	ns
HIGH to LOW propagation delay	t _{PHL}	MR to Qn; see Figure 8	V _{CC} =2.0V	-	-	235	ns
			V _{CC} =4.5V	-	-	47	ns
			V _{CC} =5.0V; C _L =15pF	-	-	-	ns
			V _{CC} =6.0V	-	-	40	ns
transition time	t _t	see Figure 7	V _{CC} =2.0V	-	-	119	ns
			V _{CC} =4.5V	-	-	22	ns
			V _{CC} =6.0V	-	-	19	ns



			CC	-			
			V _{CC} =2.0V	105	-	-	ns
pulse width	t _w	LE HIGH or LOW; see Figure 7	V _{CC} =4.5V	21	-	-	ns
			V _{CC} =6.0V	18	-	-	ns
			V _{CC} =2.0V	105	-	-	ns
		MR LOW; see Figure 8	V _{CC} =4.5V	21	-	-	ns
			V _{CC} =6.0V	18	-	-	ns
			V _{CC} =2.0V	120	-	-	ns
set-up time	t _{su}	D, An to LE; see Figure 9 and Figure 10	V _{CC} =4.5V	24	-	-	ns
			V _{CC} =6.0V	20	-	-	ns
			V _{CC} =2.0V	0	-	-	ns
hold time	t _h	D to LE; see Figure 9 and Figure 10	V _{CC} =4.5V	0	-	-	ns
			V _{CC} =6.0V	0	-	-	ns
			V _{CC} =2.0V	2	-	-	ns
		An to LE; see Figure 9 and Figure 10	V _{CC} =4.5V	2	-	-	ns
			V _{CC} =6.0V	2	-	-	ns
			V _{CC} =2.0V	2	-	-	ns
power dissipation capacitance	C _{PD}	f _i =1MHz; V _I =GND to V _{CC}		-	-	-	pF

Note:

[1] Typical values are measured at nominal supply voltage (V_{CC}=3.3V and V_{CC}=5.0V).

[2] t_{pd} is the same as t_{PLH} and t_{PHL}.

[3] t_t is the same as t_{THL} and t_{TLH}.

[4] C_{PD} is used to determine the dynamic power dissipation (P_D in uW).

$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \sum (C_L \times V_{CC}^2 \times f_o)$ where:

f_i=input frequency in MHz;

f_o=output frequency in MHz;

C_L=output load capacitance in pF;

V_{CC}=supply voltage in V;

N=number of inputs switching;

$\sum (C_L \times V_{CC}^2 \times f_o)$ =sum of outputs.



4、Testing Circuit

4.1、AC Testing Circuit

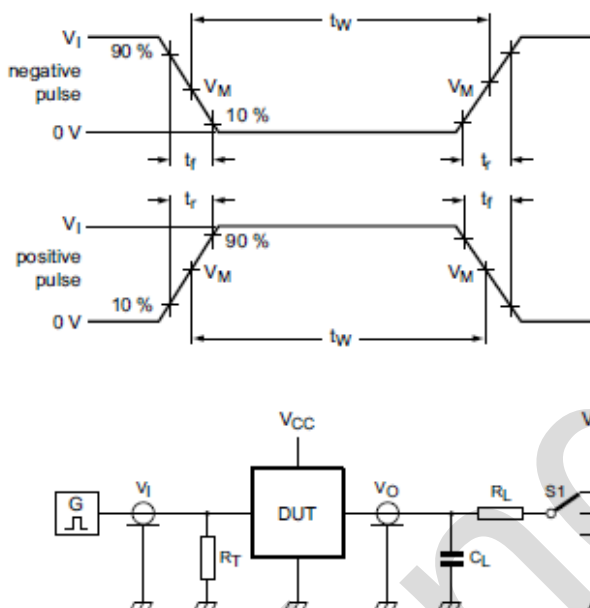


Figure 4. Test circuit for measuring switching times

Definitions for test circuit:

C_L =Load capacitance including jig and probe capacitance.

R_T =Termination resistance should be equal to the output impedance Z_o of the pulse generator.

R_L =Load resistance.

S1=Test selection switch.

4.2、AC Testing Waveforms

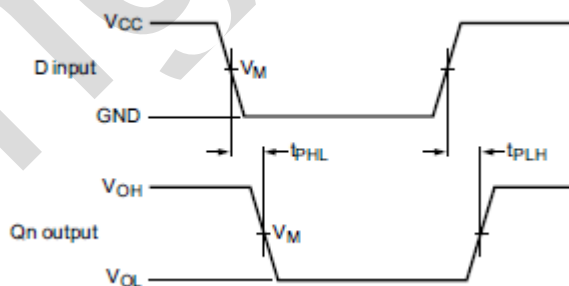


Figure 5. Data input to output propagation delays

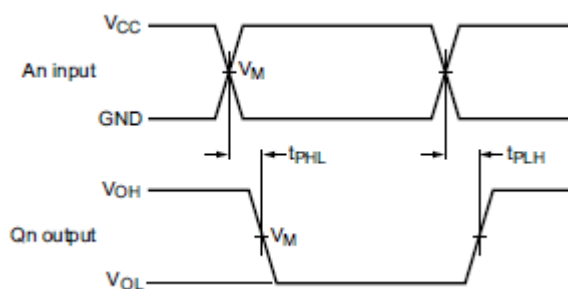


Figure 6. Address input to output propagation delays

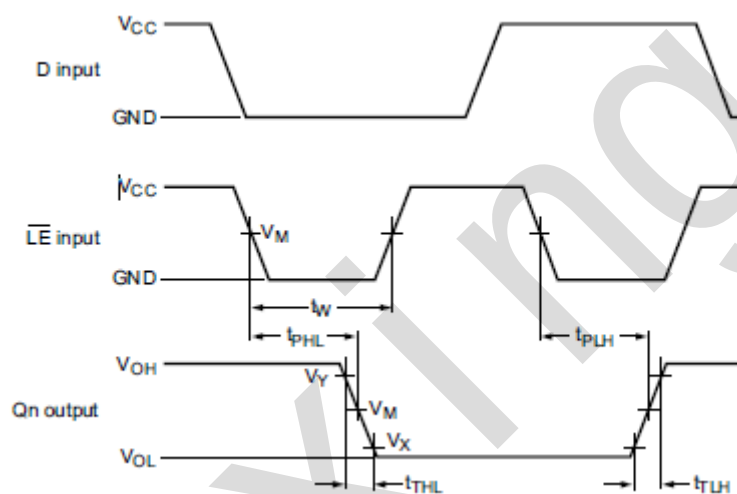


Figure 7. Enable input to output propagation delays and pulse width

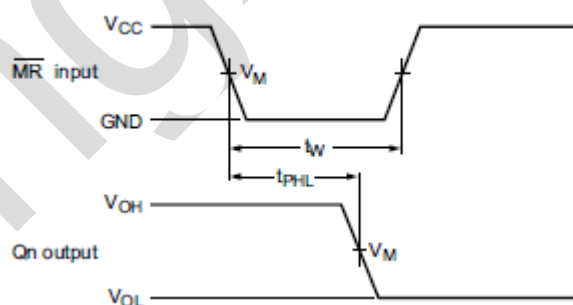


Figure 8. Master reset input to output propagation delay

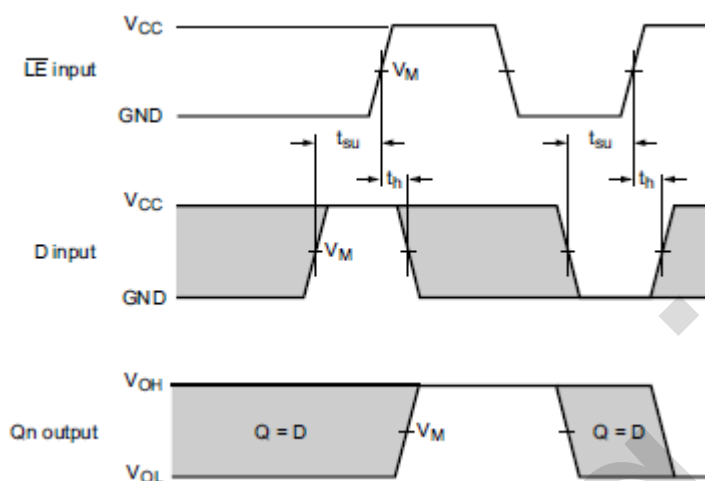


Figure 9. Data input to latch enable input set-up and hold times

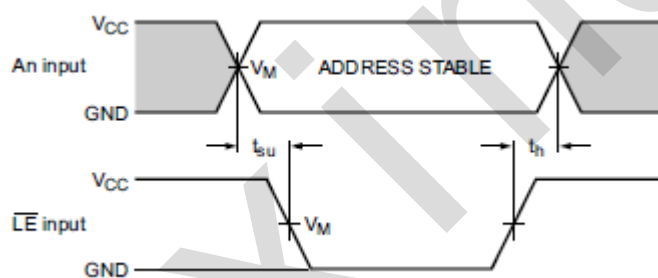


Figure 10. Address input to latch enable input set-up and hold times

4.3、Measurement Points

Input	Output		
V_M	V_M	V_X	V_Y
$0.5 \times V_{CC}$	$0.5 \times V_{CC}$	$0.1 \times V_{CC}$	$0.9 \times V_{CC}$

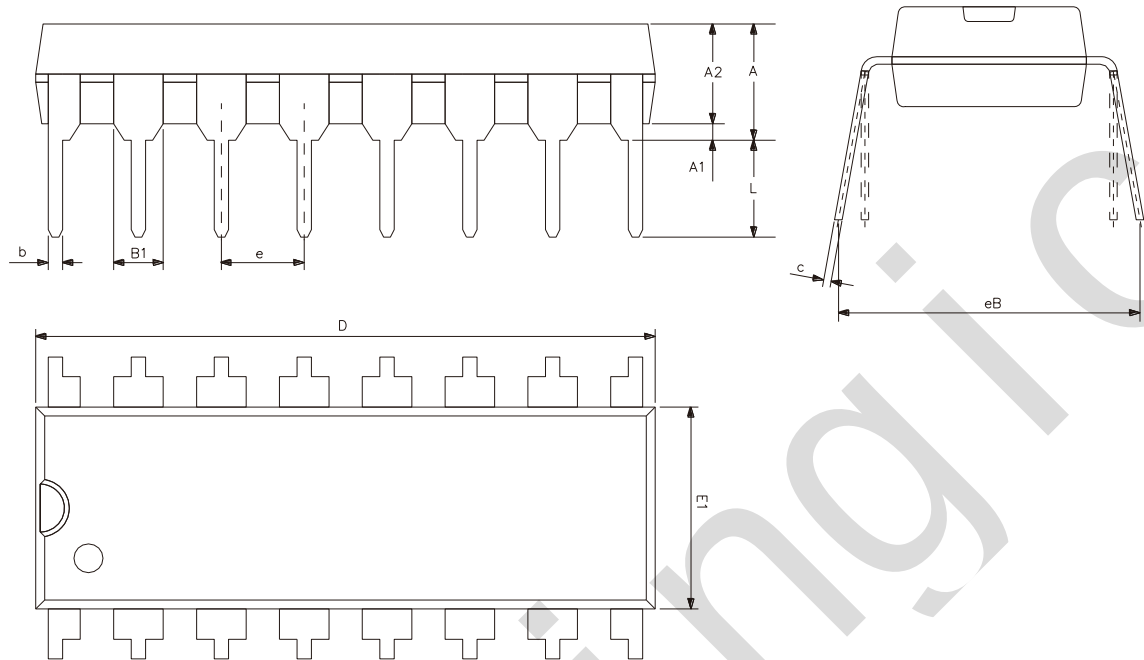
4.4、Test Data

Input		Load		S1 position
V_I	t_r, t_f	C_L	R_L	t_{PHL}, t_{PLH}
V_{CC}	6ns	15pF, 50pF	1k Ω	open



5、Package Information

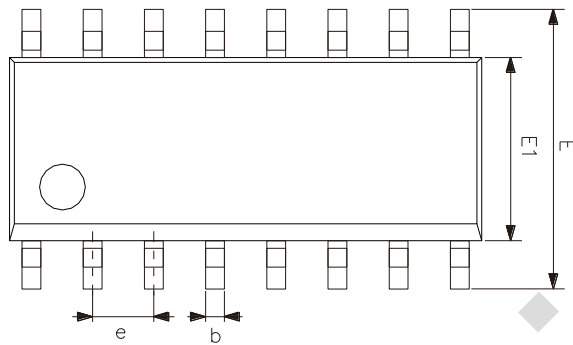
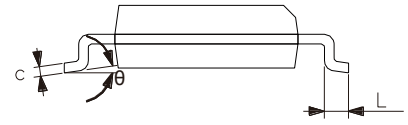
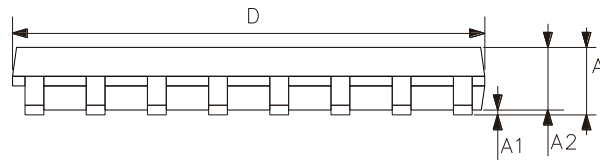
5.1、DIP16



Symbol	Dimensions (mm)	
	Min.	Max.
A2	3.20	3.60
A1	0.51	-
A	3.60	5.33
L	3.00	3.60
b	0.36	0.56
B1	1.52	
D	18.80	19.94
E1	6.20	6.60
e	2.54	
c	0.20	0.36
eB	7.62	9.30



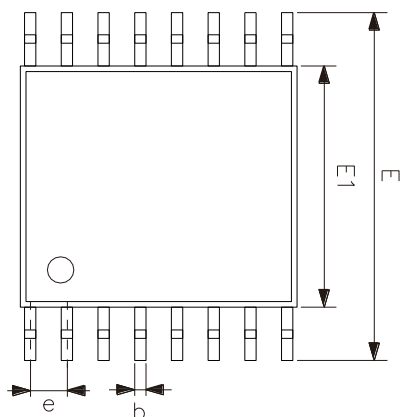
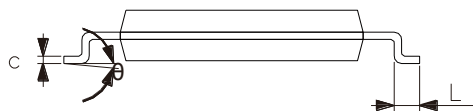
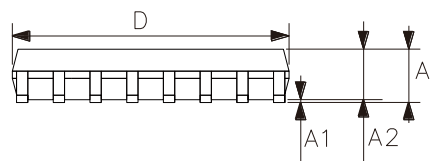
5.2、SOP16



Symbol	Dimensions (mm)	
	Min.	Max.
A	1.35	1.80
A1	0.10	0.25
A2	1.25	1.55
b	0.33	0.51
c	0.19	0.25
D	9.50	10.10
E	5.80	6.30
E1	3.70	4.10
e	1.27	
L	0.35	0.89
θ	0°	8°



5.3、TSSOP16



Symbol	Dimensions (mm)	
	Min.	Max.
A	-	1.20
A1	0.05	0.15
A2	0.80	1.05
b	0.19	0.30
c	0.09	0.20
D	4.90	5.10
E1	4.30	4.50
E	6.20	6.60
e	0.65	
L	0.45	0.75
θ	0°	8°



6、Statements And Notes

6.1、The name and content of Hazardous substances or Elements in the product

Part name	Hazardous substances or Elements									
	Lead and lead compounds	Mercury and mercury compounds	Cadmium and cadmium compounds	Hexavalent chromium compounds	Polybrominated biphenyls	Polybrominated biphenyl ethers	Dibutyl phthalate	Butylbenzyl phthalate	Di-2-ethylhexyl phthalate	Diisobutyl phthalate
Lead frame	○	○	○	○	○	○	○	○	○	○
Plastic resin	○	○	○	○	○	○	○	○	○	○
Chip	○	○	○	○	○	○	○	○	○	○
The lead	○	○	○	○	○	○	○	○	○	○
Plastic sheet installed	○	○	○	○	○	○	○	○	○	○
explanation	○: Indicates that the content of hazardous substances or elements in the detection limit of the following the SJ/T11363-2006 standard. ×: Indicates that the content of hazardous substances or elements exceeding the SJ/T11363-2006 Standard limit requirements.									

6.2、Notes

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